

Fraunhofer-Institut für Integrierte Systeme und Bauelementetechnologie IISB

Lithography and optics simulation now and in future

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Dr. Lithography Simulation

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Lithography simulation

What is it all about



Lithography scanner @ 193 nm immersion

Simulation model

Lithography simulation

How to make smaller and smaller structures

λ NA $\mathbf{x}_{\min} = \mathbf{C}\mathbf{D} = \mathbf{k}_1$



Imaging with a stepper/scanner @ 193 nm





Computational lithography and optics group

What are we doing

- Simulation and optimization of lithographic processes for optical and EUV lithography, Mask-Aligner and alternative exposures
- Rigorous simulation of light diffraction and imaging of nanostructures (highly accurate physical models, Maxwell equations, Fourier optics)
- Optimization of optical components and processes (genetic optimizer and others)
- Application of AI algorithms in lithography and optics
- Modeling of physical and chemical phenomena in photoresists
- Main research tool: Dr. Litho







Mask defect and repair assessment for next generation EUV lithography

Physical lithography simulations + AI methods to deal with big and strongly varying data



- Defect detection from SEM images with CNN
- Defect shape determination (CNN + analytical method)

SEM images from Zeiss in the framework of the PIn3S project



 Accurate contour extraction from SEM images (CNN + analytical method)



Defect shape and contours

3D mask with/without repair



- Transformation of SEM contours into 3D lithography mask
- Application of repair
- Lithographic assessment of defect and repair with highly accurate Dr.LiTHO simulations



European project PIn3S

Mask simulation with data driven and physics informed AI methods

To tackle the more and more severe simulation time issue of physical mask simulations







Optimization of EUV system components

Highly accurate lithography simulations and optimizations for next generation systems



optics, support of Zeiss SMT in optical systems design

Modeling, characterization and optimization of novel absorber materials for EUV masks, cooperation with imec and Zeiss SMS



Multi-objective optimization for next generation high NA EUV lithography

Combination of highly accurate litho simulations with multi-objective genetic optimizer



Cooperation with ASML

Multiple system parameter solutions (mask absorber, illumination and more) to optimize imaging performance with multiple quality measures (nilsE, DoF and more)



AI based prediction of pattern collapse in resist processes

Combining litho simulations, mechanical simulations and AI methods for more holistic investigations



Combination of lithography simulation (optical simulation + resist simulation) and mechanical simulation (tension, pressure, displacement) for the generation of AI training data

Bilateral cooperation



Modeling of direct laser writing for nanoscale 3D topography

Extended (litho) simulation models for applications beyond classical lithography



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Simulation





Simulation and optimization of light propagation in a double waveguide with grating coupler



First steps towards future application fields Adaptation of optical (litho) models to photonic devices

Conclusions

- Today, the models of the Fraunhofer IISB litho group are used for the simulation, investigation and optimization of next generation EUV lithography components and processes and for applications beyond the classical lithography like direct laser writing
- First adaptations of the models towards the simulation and optimization of photonic devices are available and could be a promising future application field
- Highly accurate physical simulations are still essential for the detailed investigation and optimization of current and future lithography systems
- The combination of physical simulations with AI methods is essential to deal with the growing amount of data and with more and more severe simulation time issues and to allow more comprehensive simulation approaches in the future





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